Print

📴 Share

**Quick Links** 

Pricing & Availability Search for Tooling

▶ Product Feature Selector

Contact Us About This Product



Have a Question? Chat with a Product Information Specialist

What can we help you find?

Email

**Products Industries** Resources **About TE My Account Innovation Support Center** 

# 1-1825094-3 Product Details



# Product Highlights:

- Socket Style = Standard
- Through Hole Contact Termination Type
- 2.54 mm Centerline
- Row-to-Row Spacing = 7.87 mm
- 14 Positions

View all Features

Add to My Part List Request Sample Find Similar Products

#### **Buy Product**

# **Documentation & Additional Information**

#### **Product Drawings:**

1-1825094-3

TE Internal Number: 1-

1825094-3 Active

 DIP SOCKET ASSY, LADDER, DIPLOMATE, .300 CL, LEAD FREE (PDF, English)

#### Catalog Pages/Data Sheets:

• None Available

#### **Product Specifications:**

None Available

# **Application Specifications:**

• DIPLOMATE Dual Leaf (DL) Low-Profile DIP Sockets (PDF, English)

#### **Instruction Sheets:**

• None Available

#### CAD Files:

• None Available

# List all Documents

# **Additional Information:**

Product Line Information

#### **Related Products:**

Tooling

# Product Features (Please use the Product Drawing for all design activity)

#### **Product Type Features:**

- Socket Style = Standard
- Profile = Standard
- Frame Style = Ladder
- Leg Style = Straight
- Color = Black

### **Electrical Characteristics:**

- Insulation Resistance (M $\Omega$ ) = 10,000
- Contact Resistance  $(m\Omega) = 30$

#### **Termination Features:**

- Contact Termination Type = Through Hole
- Termination Post Length (mm [in]) = 3.25 [0.128]
- Solder Tail Contact Plating = Tin

• Height Above PC Board (mm [in]) = 5.33 [0.210]

# **Body Features:**

#### **Housing Features:**

- Centerline (mm [in]) = 2.54 [0.100]
- Housing Material = Thermoplastic GF
- UL Flammability Rating = UL 94V-0

#### **Configuration Features:**

• Number of Positions = 14

## **Industry Standards:**

- RoHS/ELV Compliance = RoHS compliant, ELV compliant
- Lead Free Solder Processes = Wave solder capable to 240°C, Wave solder capable to 260°C, Wave solder capable to 265°C
- RoHS/ELV Compliance History = Always was RoHS compliant

# **Conditions for Usage:**

• Temperature Range (°C) = 125

- Row-to-Row Spacing (mm [in]) = 7.87 [0.310]
- Mount Style = Vertical

#### **Contact Features:**

- Contact Base Material = Beryllium Copper
- Contact Plating, Mating Area, Material = Gold (30)
- Contact Style = Stamped + Formed
- Mating Contact Type = Dual Leaf

## Operation/Application:

• Application = Production

#### **Packaging Features:**

• Packaging Method = Tube

# Other:

- Brand = TE Connectivity
- Proprietary Name = DIPLOMATE DL
- Comment = ONLY sockets with straight solder tails are recommended for automatic insertion.

**Corporate Information** 

About TE Investors **News Room** Supplier Portal

Careers Terms & Conditions Privacy Policy

**Quick Links** 

**Distributor Inventory Product Cross Reference** Documents & Drawings

Product Compliance Support Center

Site Map

**Customer Support** 

Email or Chat With Us Find a Phone Number Knowledge Base Manage Your Account

**Keep Me Informed** 















© 2013 Tyco Electronics Corporation, a TE Connectivity Ltd. company. All Rights Reserve

Provide Website Feedback

